

JX400N1700MK4

1700V, 400A, 6.5mΩ, Half-Bridge, Silicon Carbide MOSFET Module



Product Data Sheet

JX-3T03-19A A/1

General Description

The JX-MED module incorporates JX's 1700V Gen3 N-channel SiC MOSFET. NTC temperature sensor inside.

Features

- High Temperature, Humidity, and Bias Operation
- Ultra Low Loss
- High-frequency Operation
- Zero Turn-off Tail Current from MOSFET
- Normally-off, Fail-safe Device Operation
- Copper Baseplate and Aluminum Nitride Insulator



Applications

- High Power Converters
- Motor Drives
- Servo Drives
- UPS Systems
- Wind Turbines

Ordering Informations

Order Number / Marking	JX400N1700MK4
Package Type	MED

Key Parameters

Symbol	Parameter	Values			Unit	Test Conditions
Absolute maximum rating						
V _{DS}	Drain-source Voltage	1700			V	T _C =25°C
I _b	Drain Current (continuous)	400			A	T _C =25°C
T _J	Junction Temperature	175			oC	
Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
Static characteristics						
R _{DS(on)}	Static Drain-source on Resistance	-	6.5	7.5	mΩ	V _{GS} =18V; I _D =200A; T _C =25°C
Dynamic characteristics						
Q _G	Total Gate Charge	-	672	-	nC	V _{DD} =1200V; V _{GS} =-5/+20V; I _D =200A; T _C =25°C
Q _{GD}	Gate-drain Charge	-	200	-		
Source-drain diode						
Q _{RR}	Reverse Recovery Charge	-	1345	-	nC	V _{GS} =-5/+18V; I _F =200A; V _R =1200V; R _{G(off)} =5Ω; Load=100μH; T _J =25°C

Absolute Maximum Ratings (at $T_c=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Values	Unit
V_{DS}	Drain-source Voltage	1700	V
V_{GS}	Gate-source Voltage (dynamic)	-10/+22	V
I_D	Drain Current (continuous)	400	A
I_{DM}	Drain Current (pulsed)	800	A
T_{op}, T_{stg}	Operating and Storage Temperature Range	-40 to +175	$^{\circ}\text{C}$
T_J	Junction Temperature	175	$^{\circ}\text{C}$
L_{Stray}	Stray Inductance	20	nH
V_{isol}	Isolation Test Voltage (DC; 2mA; t=10s)	4.2	kV
$R_{th Jh}$	Thermal Resistance, Junction-to-heatsink	0.13	$^{\circ}\text{C/W}$

MOSFET Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
Static characteristics (at $T_c=25^{\circ}\text{C}$ unless otherwise specified)						
BV_{DS}	Drain-source Breakdown Voltage	1700	-	-	V	$V_{GS}=0\text{V}$
I_{DSS}	Zero Gate Voltage Drain Current	-	-	200	μA	$V_{DS}=1700\text{V}; V_{GS}=0\text{V}$
I_{GSS}	Gate-body Leakage Current	-	-	2.00	μA	$V_{GS}=-10/20\text{V}; V_{DS}=0\text{V}$
$V_{GS(th)}$	Gate Threshold Voltage	2.0	-	4.0	V	$V_{DS}=V_{GS}; I_D=40\text{mA}$
$R_{DS(on)}$	Static Drain-source on Resistance	-	6.5	7.5	$\text{m}\Omega$	$V_{GS}=18\text{V}; I_D=200\text{A}$
$V_{GS(on)}$	Recommended Turn-on Voltage	-	18	-	V	Static
$V_{GS(off)}$	Recommended Turn-off Voltage	-	-5	-	V	
R_G	Gate Resistance	-	1.1	-	Ω	$V_{AC}=25\text{mV}; f=1\text{MHz}$
Dynamic characteristics (at $T_c=25^{\circ}\text{C}$ unless otherwise specified)						
C_{iss}	Input Capacitance	-	25.9	-	nF	$V_{DS}=1200\text{V}; f=100\text{kHz}; V_{AC}=25\text{mV}$
C_{oss}	Output Capacitance	-	0.79	-		
C_{rss}	Reverse Transfer Capacitance	-	64	-	pF	
E_{on}	Turn-on Energy	-	18.1	-	mJ	$V_{DD}=1200\text{V}; V_{GS}=-5/+18\text{V}; I_D=200\text{A}; R_{G(ext)}=5.0\Omega; \text{Load}=100\mu\text{H}$
E_{off}	Turn-off Energy	-	10.5	-		
Q_{GS}	Gate-source Charge	-	208	-	nC	$V_{DD}=1200\text{V}; V_{GS}=-5/+20\text{V}; I_D=200\text{A}$
Q_{GD}	Gate-drain Charge	-	200	-		
Q_G	Total Gate Charge	-	672	-		
$t_{d(on)}$	Turn-on Delay Time	-	102	-	ns	$V_{DD}=1200\text{V}; V_{GS}=-5/+18\text{V}; I_D=200\text{A}; R_{G(ext)}=5.0\Omega; \text{Load}=100\mu\text{H}$
t_r	Rise Time	-	55	-		
$t_{d(off)}$	Turn-off Delay Time	-	278	-		
t_f	Fall Time	-	81	-		

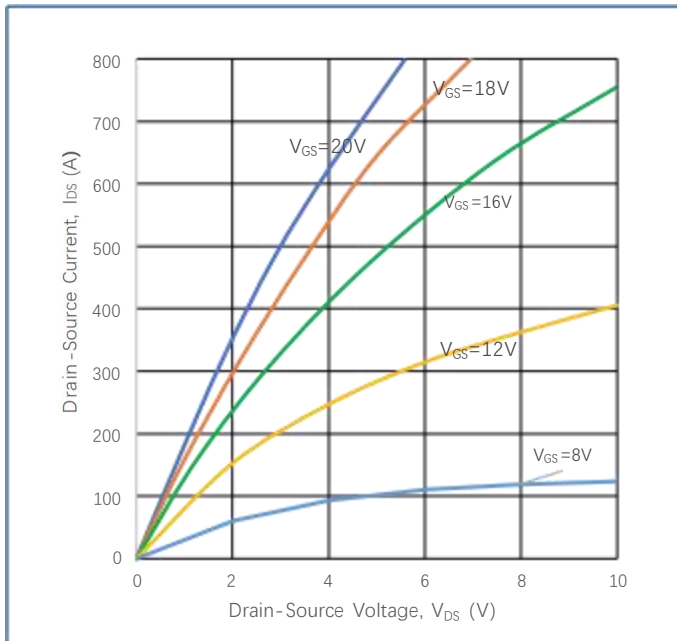
Body Diode Characteristics (at T_J=25°C unless otherwise specified)

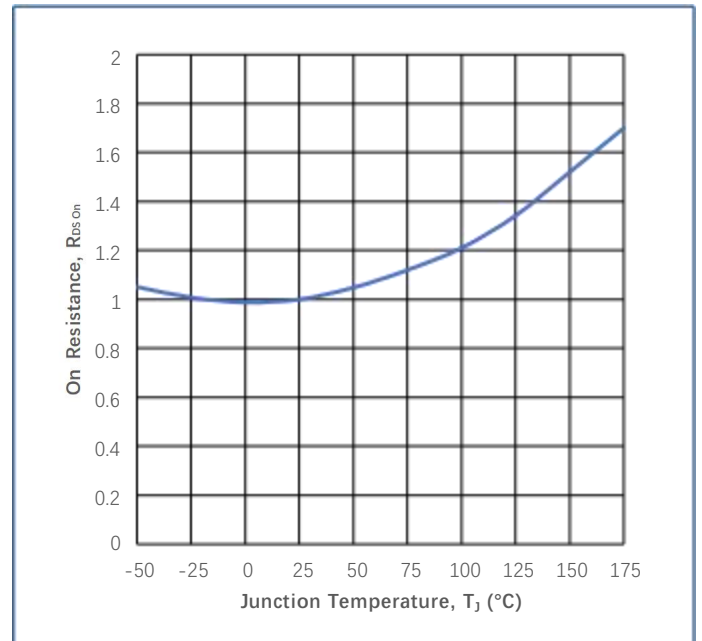
Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
V _{FSD}	Forward Voltage	-	-	6	V	V _{GS} =0V; I _F =200A
I _S	Continuous Diode Forward Current	-	200	-	A	V _{GS} =0V; T _C =25OC
t _{RR}	Reverse Recovery Time	-	62	-	ns	V _{GS} =-5/+18V; I _F =200A; R _{G(off)} =5Ω; V _R =1200V; Load=100μH
Q _{RR}	Reverse Recovery Charge	-	1345	-	nC	
I _{RRM}	Peak Reverse Recovery Current	-	104	-	A	

NTC Thermistor Characteristics

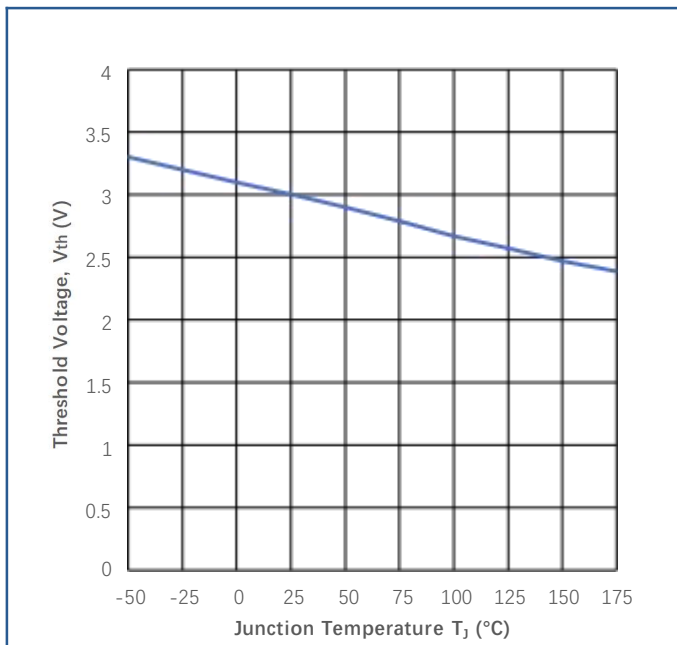
Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
R ₂₅	Rated Resistance	-	5.00	-	kΩ	T _{NTC} =25OC
ΔR/R	Deviation of R ₁₀₀	-5	-	5	%	T _{NTC} =100°C; R ₁₀₀ =493.3Ω
B _{25/50}	Beta Value for 25°C to 50°C	-	3375	-	K	R ₂ =R ₂₅ exp[B _{25/50} (1/T ₂ - 1/(298.15K))]
B _{25/80}	Beta Value for 25°C to 80°C	-	3414	-	K	R ₂ =R ₂₅ exp[B _{25/80} (1/T ₂ - 1/(298.15K))]
B _{25/100}	Beta Value for 25°C to 100°C	-	3436	-	K	R ₂ =R ₂₅ exp[B _{25/100} (1/T ₂ - 1/(298.15K))]

Typical Performance

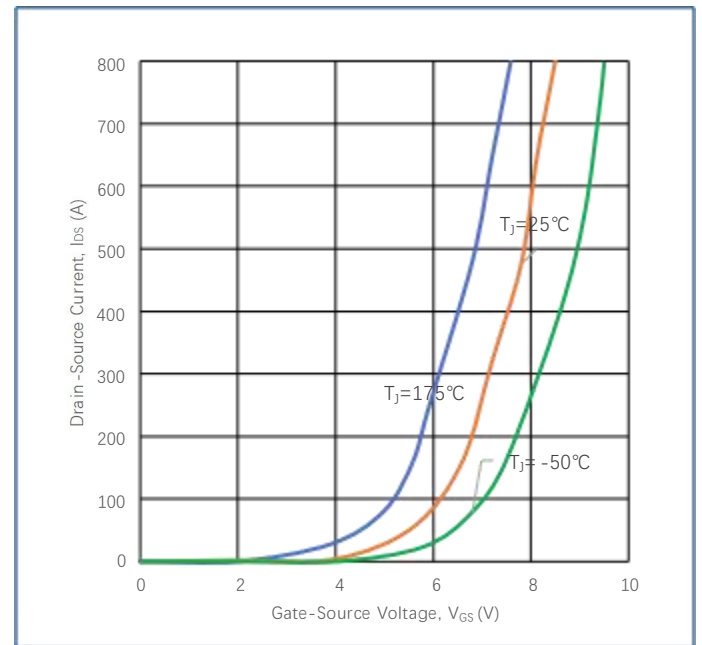

Figure 1

Output Characteristics (T_J=25 °C)

Figure 2

Normalized On-resistance vs. Temperature

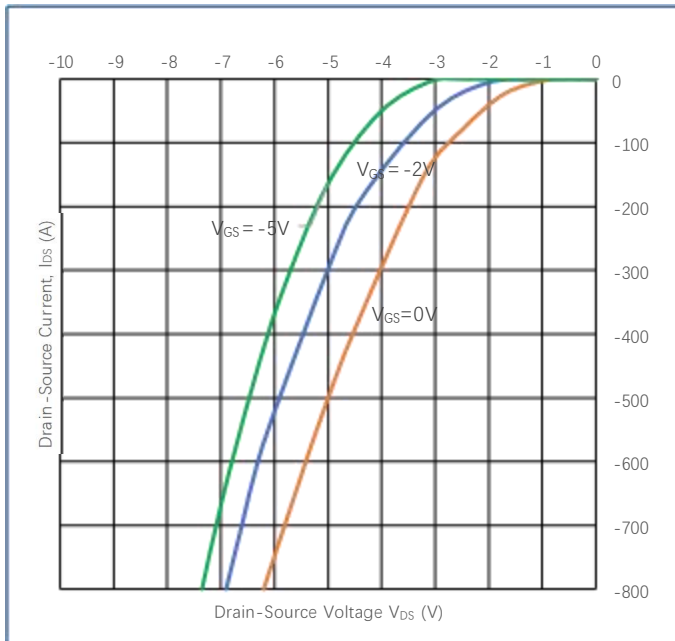

Figure 3

Threshold Voltage vs. Temperature

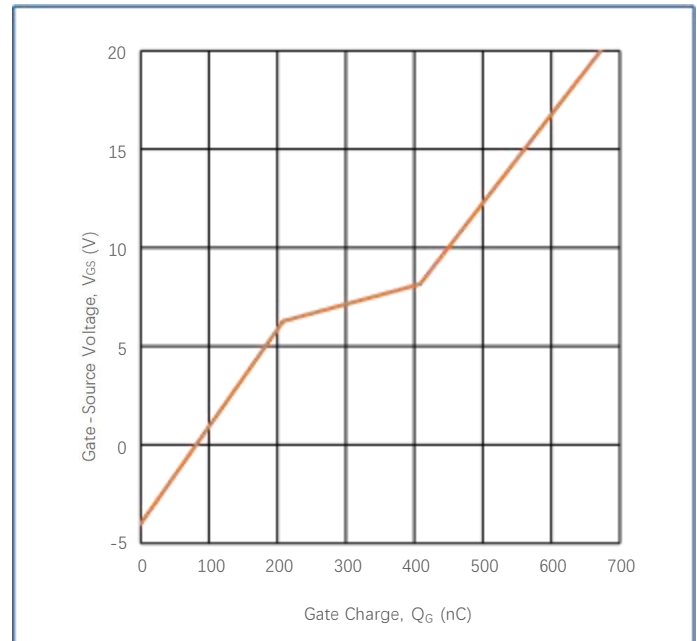

Figure 4

Transfer Characteristic for Various T_J

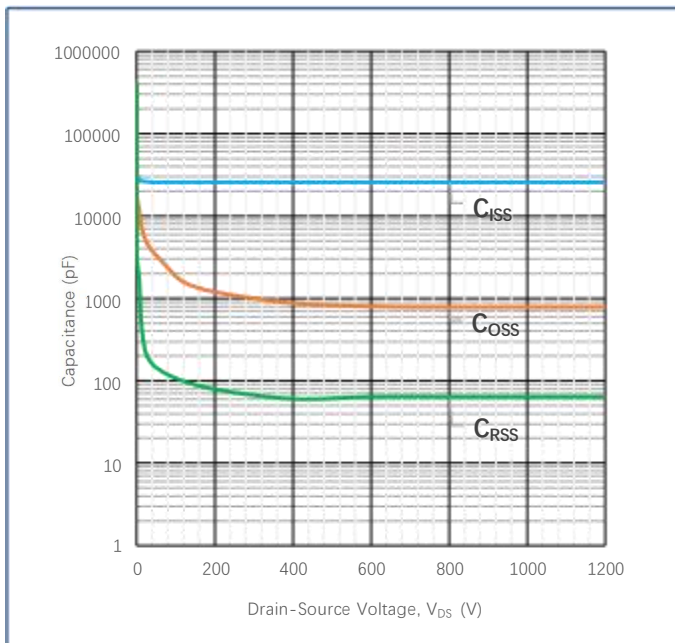
Typical Performance


Figure 5

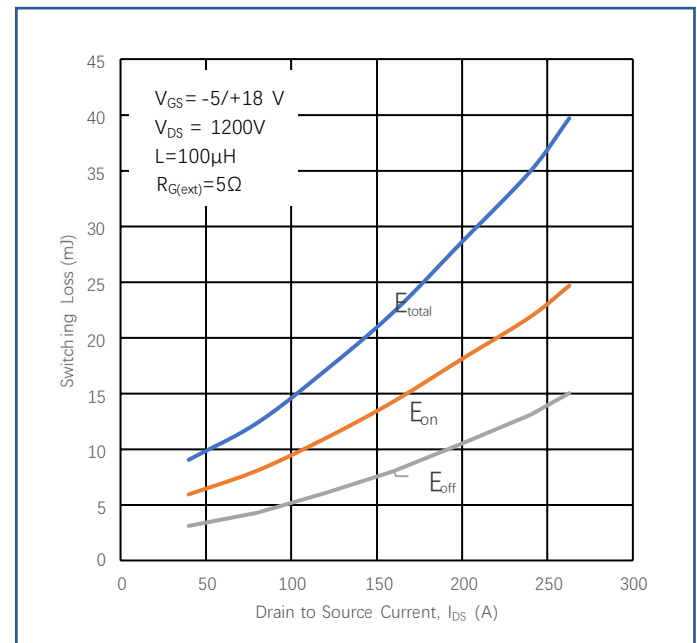
Diode Characteristic at 25 °C


Figure 6

Typical Gate Charge Characteristics


Figure 7

Typical Capacitances vs. Drain-source Voltage


Figure 8

Inductive Switching Energy vs. Drain Current

Typical Performance

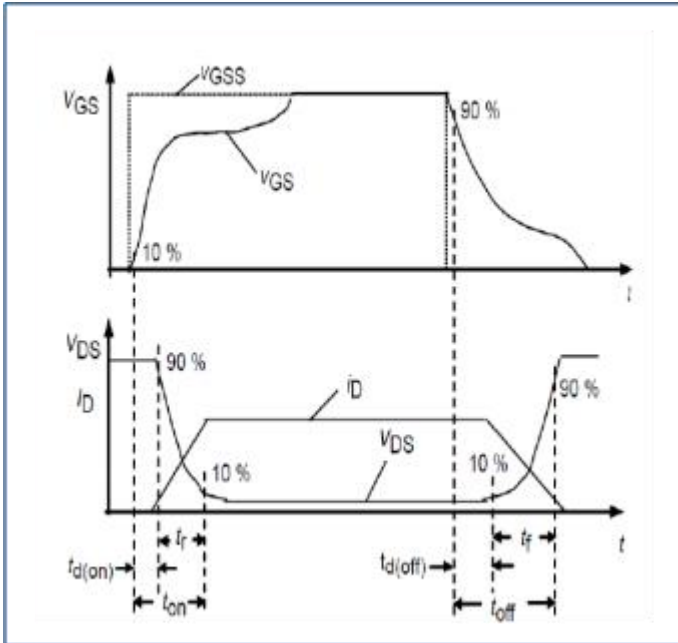


Figure 9

Switching Time Description

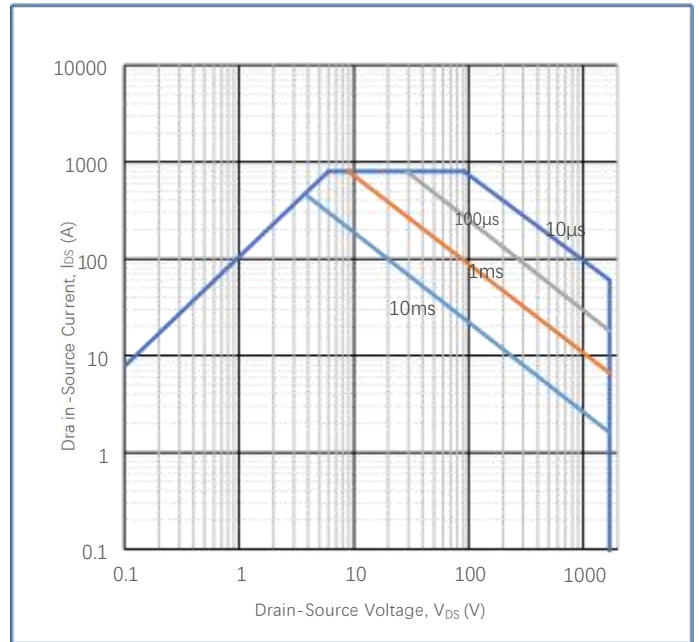
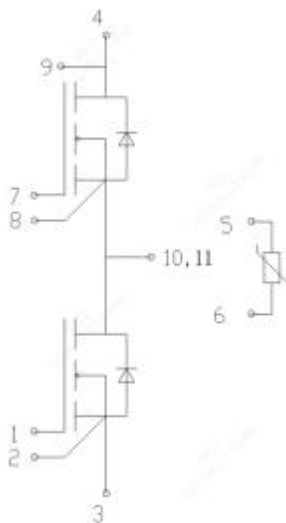


Figure 10

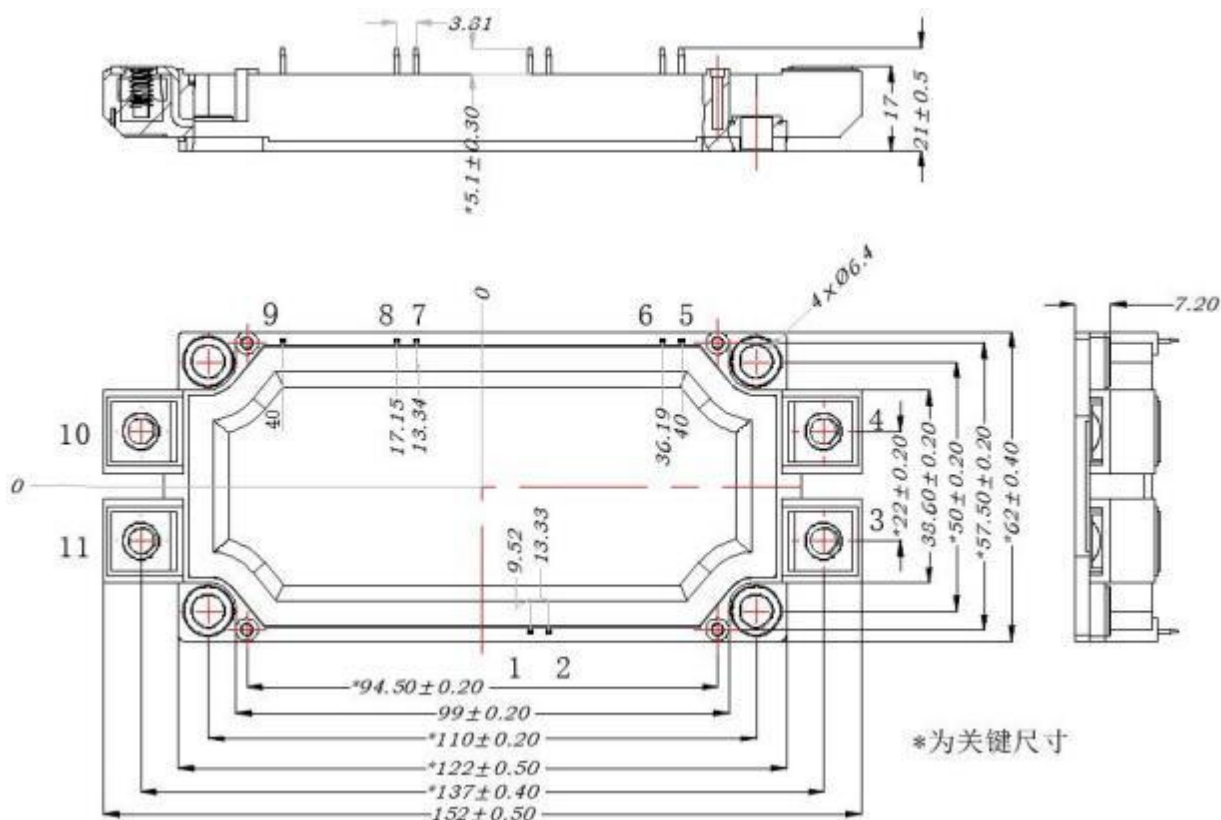
Safe Operating Area

Circuit Diagram Headline



Package Dimensions (mm)

Package Type: MED



未标注线性公差按 GB/1804-2000c 级执行	公差分段	0.5-3	3-6	6-30	30-120	120-400
	c 级	±0.2	±0.3	±0.5	±0.8	±1.2

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